

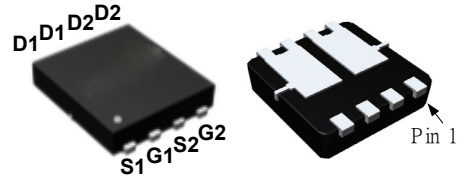
Features

- 100V/35A
 $R_{DS(ON)} = 15m\Omega (typ.) @ V_{GS} = 10V$
 $R_{DS(ON)} = 20m\Omega (typ.) @ V_{GS} = 4.5V$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free and Green Devices Available
(RoHS Compliant)

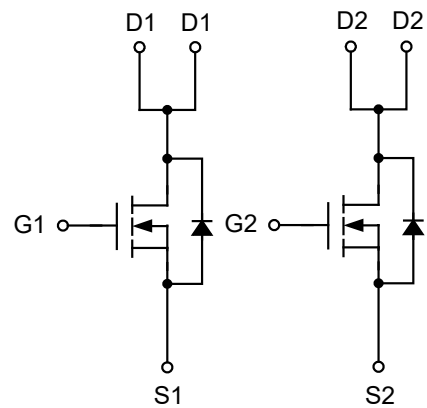
Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.

Pin Description



DFN5x6C-8_EP2



N-Channel MOSFET

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter		Rating	Unit
V_{DSS}	Drain-Source Voltage		100	V
V_{GSS}	Gate-Source Voltage		± 20	
T_J	Maximum Junction Temperature		150	C
T_{STG}	Storage Temperature Range		-55 to 150	
I_S	Diode Continuous Forward Current	$T_C=25^{\circ}\text{C}$	35	A
I_D	Continuous Drain Current	$T_C=25^{\circ}\text{C}$	35	
		$T_C=100^{\circ}\text{C}$	19	
I_{DM}^{a}	Pulse Drain Current	$T_C=25^{\circ}\text{C}$	105	A
P_D	Maximum Power Dissipation	$T_C=25^{\circ}\text{C}$	30	W
		$T_C=100^{\circ}\text{C}$	11	
$R_{\theta\text{JC}}$	Thermal Resistance-Junction to Case		4.2	$^{\circ}\text{C/W}$
I_D	Continuous Drain Current	$T_A=25^{\circ}\text{C}$	5.8	A
		$T_A=70^{\circ}\text{C}$	4.6	
P_D	Maximum Power Dissipation	$T_A=25^{\circ}\text{C}$	1.39	W
		$T_A=70^{\circ}\text{C}$	0.89	
$R_{\theta\text{JA}}^{\text{c}}$	Thermal Resistance-Junction to Ambient	Steady State	90	$^{\circ}\text{C/W}$
I_{AS}^{b}	Avalanche Current, Single pulse	$L=0.5\text{mH}$	15	A
E_{AS}^{b}	Avalanche Energy, Single pulse	$L=0.5\text{mH}$	56	mJ

Note a : Pulse width is limited by max. junction temperature.

Note b : UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature $T_J=25^{\circ}\text{C}$).

Note c : Surface Mounted on 1in^2 pad area.

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

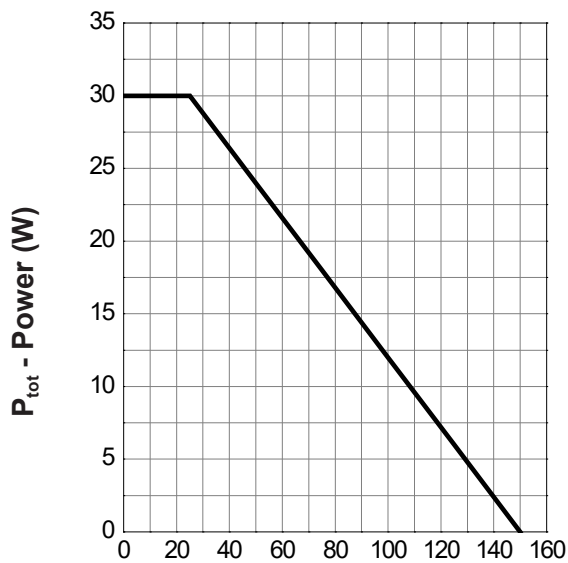
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =80V, V _{GS} =0V T _J =85°C	-	-	1 30	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	1	2	3	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^d	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =11A V _{GS} =4.5V, I _{DS} =7A	- -	15 20	19 26	mΩ
Diode Characteristics						
V _{SD} ^d	Diode Forward Voltage	I _{SD} =5A, V _{GS} =0V	-	0.8	1.3	V
t _{rr}	Reverse Recovery Time	I _{SD} =11A, dI _{SD} /dt=100A/μs	-	38	-	ns
Q _{rr}	Reverse Recovery Charge		-	58	-	nC
Dynamic Characteristics ^e						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	2	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =50V, Frequency=1.0MHz	-	1150	1500	pF
C _{oss}	Output Capacitance		-	180	-	
C _{rss}	Reverse Transfer Capacitance		-	28	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =30V, R _L =30Ω, I _{DS} =1A, V _{GEN} =10V, R _G =6Ω	-	14	26	ns
t _r	Turn-on Rise Time		-	7	13	
t _{d(OFF)}	Turn-off Delay Time		-	32	58	
t _f	Turn-off Fall Time		-	31	56	
Gate Charge Characteristics ^e						
Q _g	Total Gate Charge	V _{DS} =50V, V _{GS} =10V, I _{DS} =11A	-	24	34	nC
Q _g	Total Gate Charge	V _{DS} =50V, V _{GS} =4.5V, I _{DS} =11A	-	12	-	
Q _{gs}	Gate-Source Charge		-	4.3	-	
Q _{gd}	Gate-Drain Charge		-	5.4	-	

Note d : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

Note e : Guaranteed by design, not subject to production testing.

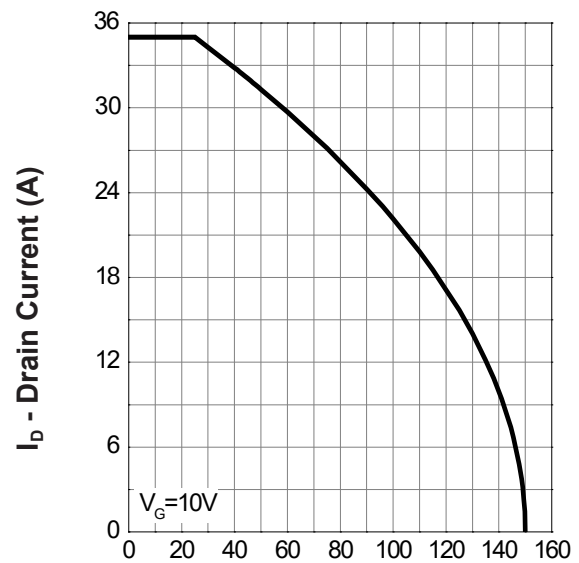
Typical Operating Characteristics

Power Dissipation



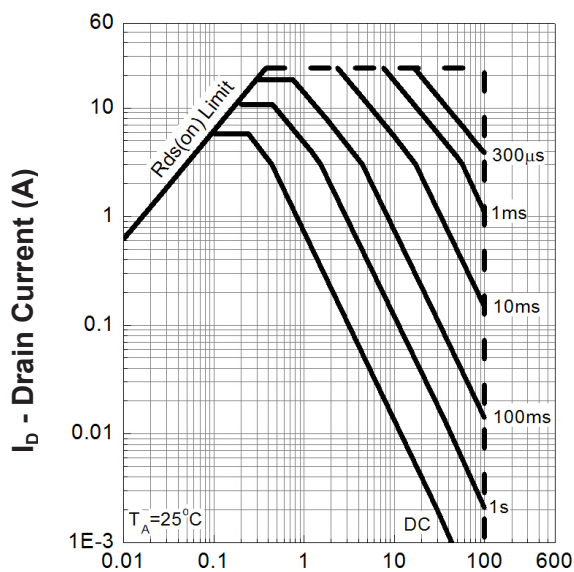
T_c - Case Temperature (°C)

Drain Current



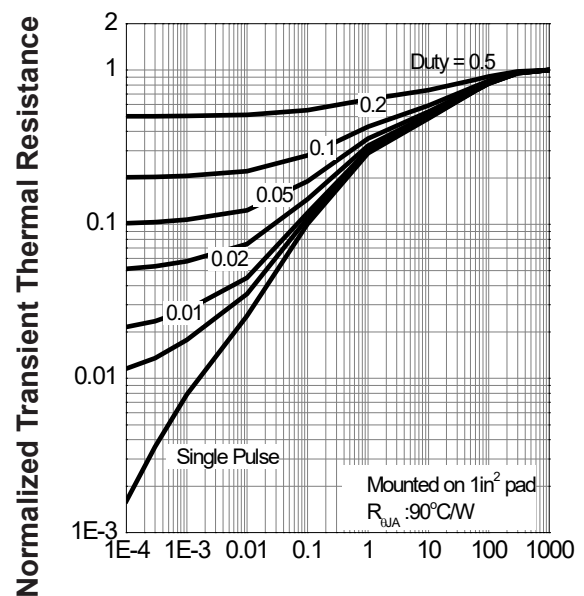
T_c - Case Temperature (°C)

Safe Operation Area



V_{DS} - Drain - Source Voltage (V)

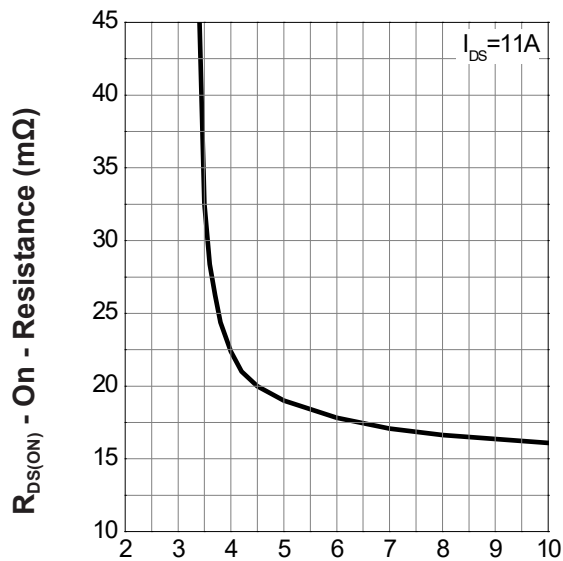
Thermal Transient Impedance



Square Wave Pulse Duration (sec)

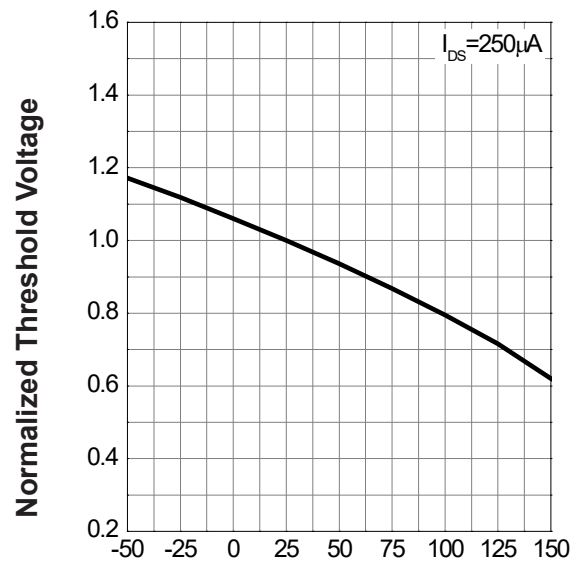
Typical Operating Characteristics(Cont.)

Gate-Source On Resistance



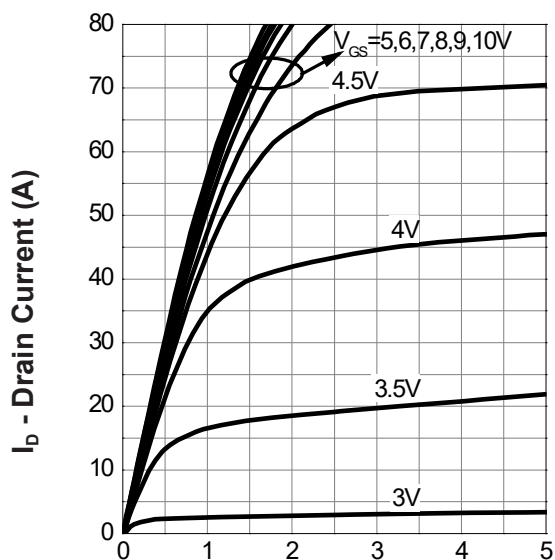
V_{GS} - Gate - Source Voltage (V)

Gate Threshold Voltage



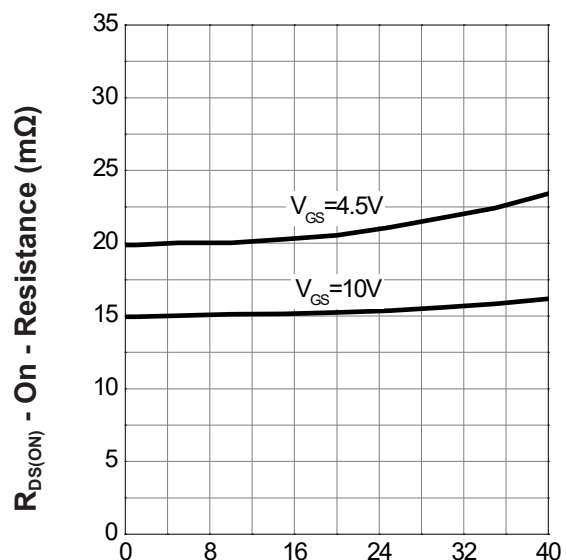
T_J - Junction Temperature (°C)

Output Characteristics



V_{DS} - Drain - Source Voltage (V)

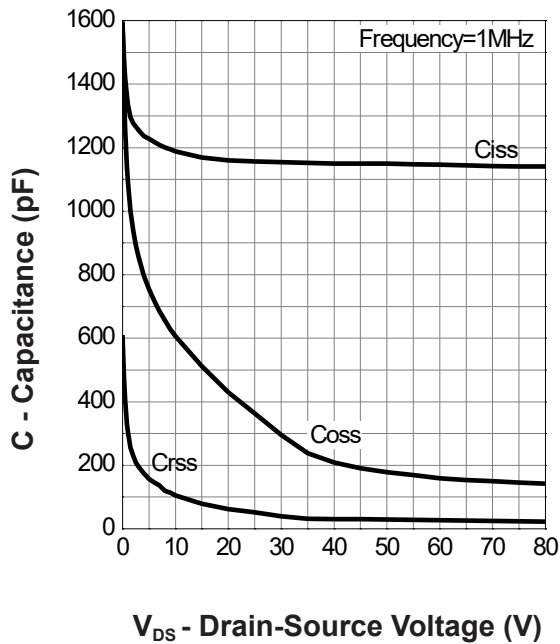
Drain-Source On Resistance



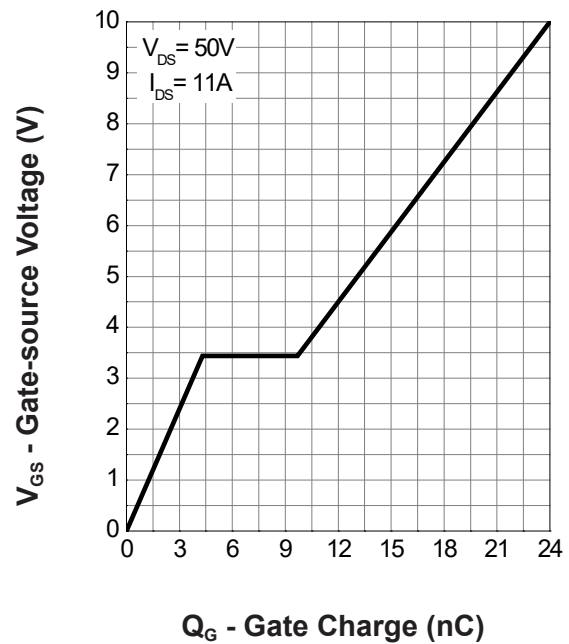
I_D - Drain Current (A)

Typical Operating Characteristics(Cont.)

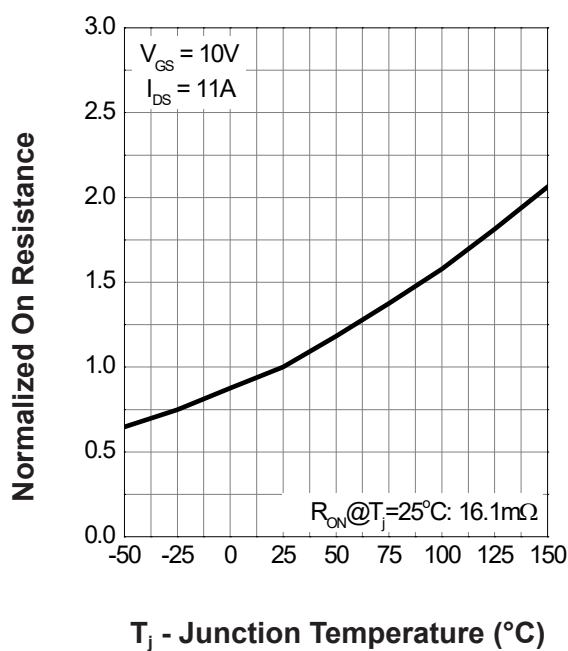
Capacitance



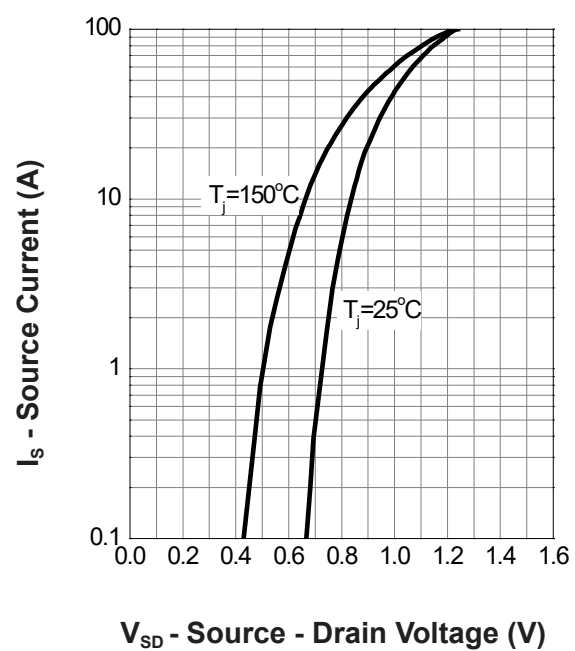
Gate Charge



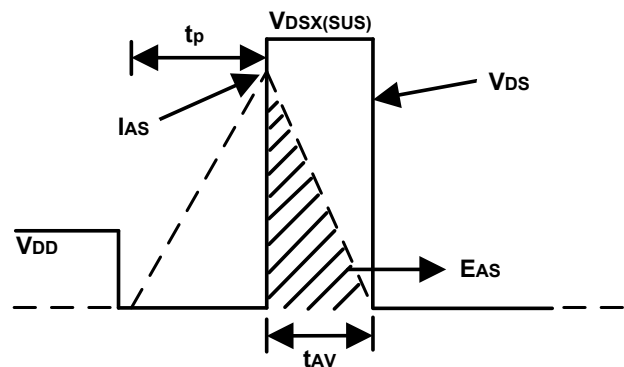
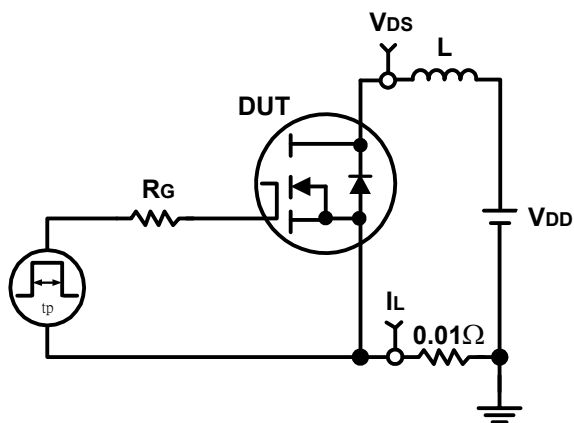
Drain-Source On Resistance



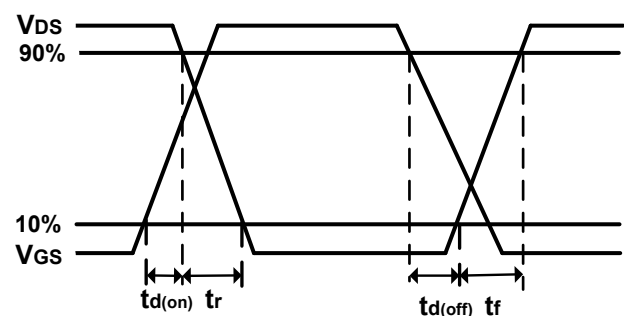
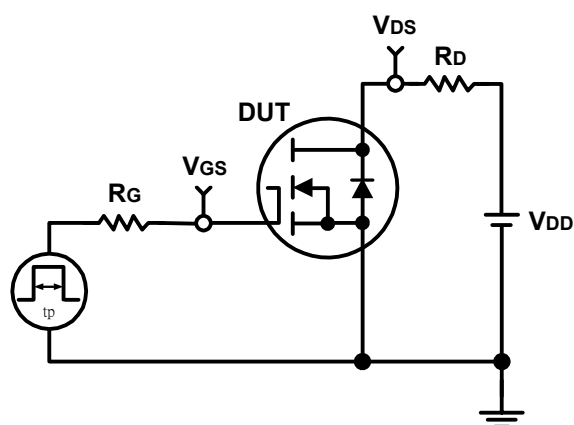
Source-Drain Diode Forward



Avalanche Test Circuit and Waveforms

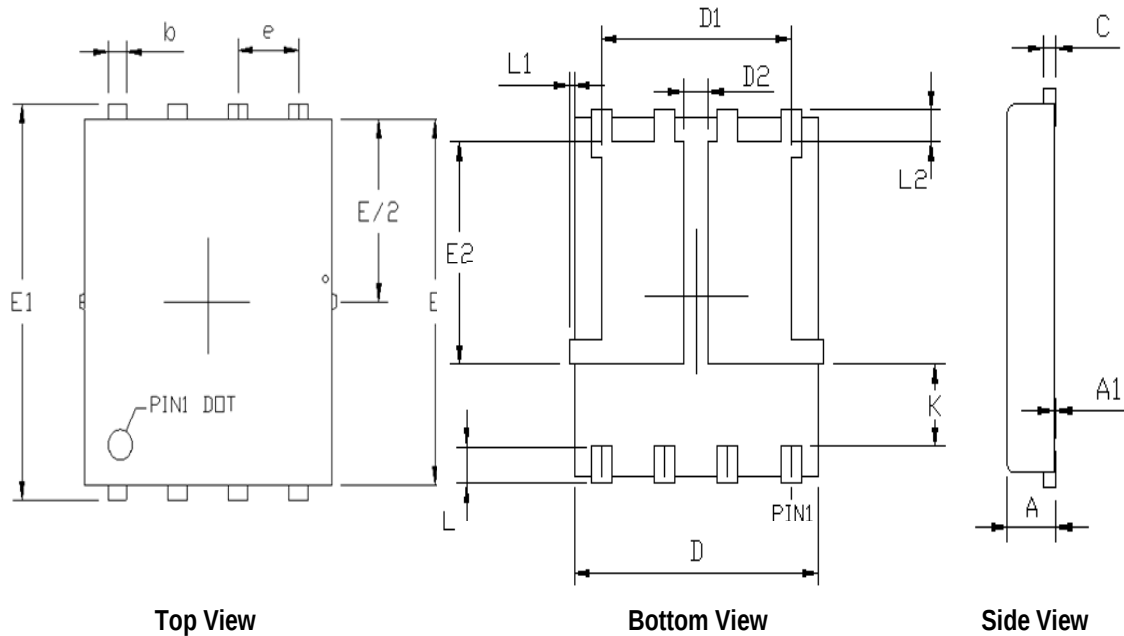


Switching Time Test Circuit and Waveforms



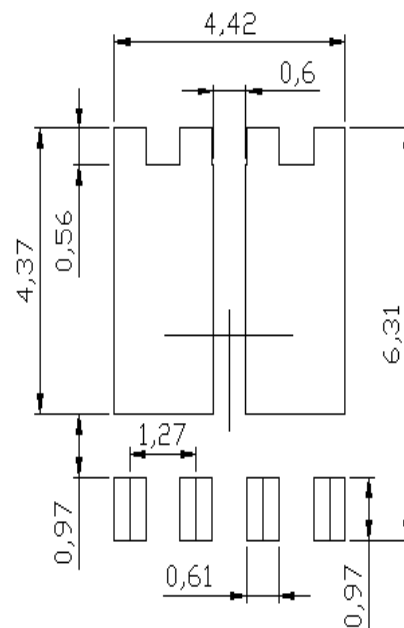
Package Information

DFN5x6C-8-EP2



SYMBOLS	DFN5x6C-8_EP2_P			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.900	1.200	0.035	0.047
A1	0.000	0.050	0.000	0.002
b	0.300	0.500	0.012	0.020
c	0.150	0.300	0.006	0.012
D	4.800	5.000	0.189	0.197
D1	3.550	4.550	0.140	0.179
D2	0.500	0.910	0.020	0.036
E	5.650	5.850	0.222	0.230
E1	5.900	6.200	0.232	0.244
E2	3.200	3.780	0.126	0.149
e	1.27 BSC		0.050 BSC	
K	1.100	-	0.043	-
L	0.500	0.800	0.020	0.031
L1	0.000	0.150	0.000	0.006
L2	0.325	0.610	0.013	0.024

RECOMMENDED LAND PATTERN



UNIT: mm